

AMENDMENTS

In the Claims

Cancel claims 3, 5-7, 30, and 37-53 without prejudice, waiver, or disclaimer.

Please substitute the following clean copy text for the pending claims of the same number.

SUB
E1
D1

1. (Thrice Amended) A microelectronic device package comprising:
a die attach pad, said pad having a bottom surface;
a plurality of substantially flat electrical connectors formed about a perimeter of said die attach pad, wherein said connectors are configured to couple a device to a substrate;
a coupling of a plurality of wires from said device package to one of said connectors;
and
an encapsulant surrounding a portion of said electrical connectors and a portion of said die attach pad, wherein said bottom surface of said die attach pad is substantially free of encapsulant.

SUB
D2 E1

23. (Once Amended) The microelectronic device package according to claim 1, wherein said wire is formed of gold wire having a diameter of approximately 25 microns.

SUB
E1
D3

35. (Once Amended) The microelectronic device package according to claim 31, wherein said frame is coated with about 10 micro inches of palladium.

36. (Once Amended) The microelectronic device package according to claim 22, wherein said device is bonded to said pad using conductive epoxy.